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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Agarwal et al.

Art Unit: 2811

Application No. 09/590,795

Filed: June 8, 2000

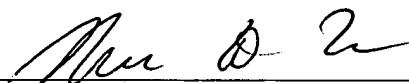
For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND TUNGSTEN
CONTAINING LAYERS

Examiner: Cuong Q. Nguyen

Date: January 6, 2003

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on January 6, 2003 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.



Attorney for Applicant

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)

COMMISSIONER FOR PATENTS
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Sir:

Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

This Information Disclosure Statement is being filed after the mailing date of a first Office action on the merits, and before the mailing date of a final Office action, a Notice of Allowance, or an action that otherwise closes prosecution, and a \$180.00 fee under 37 C.F.R. § 1.17(p) may be charged to Deposit Account No. 02-4550. If the Patent Office

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determines that an additional fee is required for to file this Information Disclosure Statement, please charge any such fees to Deposit Account No. 02-4550. **Two** copies of this Information Disclosure Statement are enclosed.

Respectfully submitted,

KLARQUIST SPARKMAN, LLP

By



Michael D. Jones
Registration No. 41,879

One World Trade Center, Suite 1600
121 S.W. Salmon Street
Portland, Oregon 97204
Telephone: (503) 226-7391
Facsimile: (503) 228-9446